

CHO-BOND® 1085 and 1086 Silicone Adhesive Primers



Customer Value Proposition:

Parker Chomerics CHO-BOND primers 1085 and 1086 are air-drying liquid coatings used to improve the adhesion of Parker Chomerics CHO-BOND conductive silicone compounds to metal and other non-silicone substrates.

The primers are moisture reactive and clear in color. CHO-BOND 1085 primer is formulated to achieve maximum adhesion on non-silicone substrates for CHO-BOND 1029 adhesive. CHO-BOND 1086 primer is formulated for use with CHO-BOND 1016, 1030, 1035, 1038, 1075 electrically conductive adhesives/sealants and CHO-THERM® 1641 thermal compound.

Note that typically, the proper primer comes bundled as a "kit" with the CHO-BOND or CHO-THERM compound ordered. However, if extra primer is deemed necessary, then part numbers for just the primer are provided in Table 2.

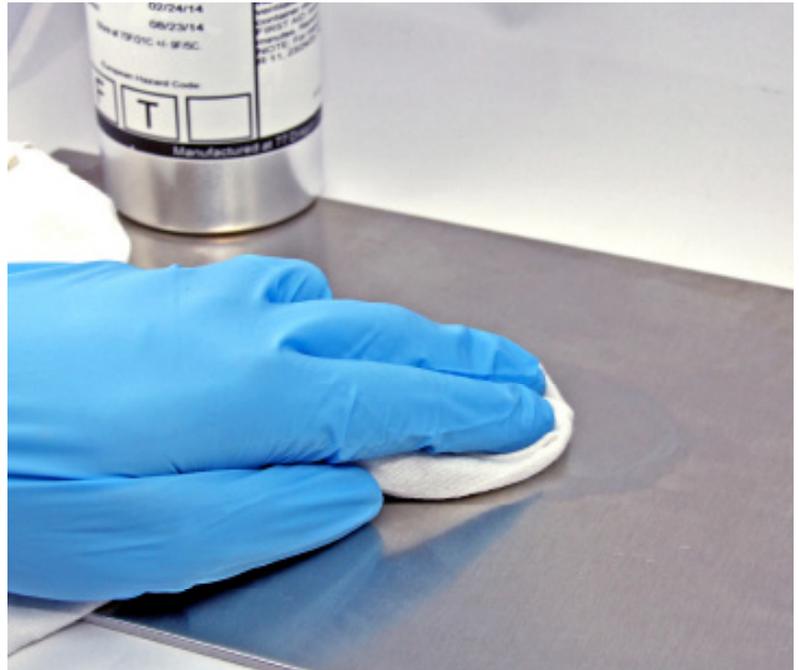
See the Conductive Compounds Selector Guide for a more detailed listing of which CHO-BOND adhesive / sealant part numbers come packaged as a kit with the primer and which do not.

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Typical Applications:

For best bonding results, use the following procedure:

1. Surfaces to be joined must be clean, dry and oil free. In a well-ventilated area, clean the substrates with isopropyl alcohol (IPA) and let the solvent flash off. (Other solvents, such as methyl-ethyl-ketone (MEK), toluene, or acetone can be used to clean difficult to remove contaminants).
2. Wet a lint-free cotton cloth with the primer and apply to the surface in horizontal and vertical strokes. Keep the surface wet at all times. A cotton swab is a common applicator for a grooved or stepped surface.

NOTE: Due to the low flash point temperature of the primer, ensure that the container is re-sealed immediately after use.

3. The primed surface must cure for 30 minutes at room temperature. A relative humidity of 40% to 70% is optimal. A low humidity level may require a longer cure time.

NOTE: There is no elevated temperature cure time for the primer.

4. Apply the CHO-BOND / CHO-THERM adhesive / sealant per that product's instructions.

NOTE: If the primer has been applied for more than 4 hours without the application of the adhesive / sealant, repeat steps 1 through 4.

CHO-BOND Primers 1085 and 1086 - Product Information

Table 1 - Typical Properties

CHO-BOND® Primers 1085 and 1086		
Typical Properties	CHO-BOND 1085	CHO-BOND 1086
Viscosity @ 25°C (77°F), centipoise	5	5
Color	Clear	Clear
Specific Gravity	0.82	0.82
Flash point, °C (°F)	14 (57)	14 (57)
Use Temperature, °C (°F)	-80 to 200 (-112 to 392)	-80 to 200 (-112 to 392)
Elevated Temperature Cure	None	None
Room Temperature Cure	0.5 hr	0.5 hr
Working Life	N/A	N/A
Shelf Life, unopened, from Date of Manufacture	9 months at 25°C (77°F)	9 months at 25°C (77°F)
Minimum thickness recommended	0.0001 in (0.00254 mm)	0.0001 in (0.00254 mm)
Maximum thickness recommended	0.0005 in (0.01270 mm)	0.0005 in (0.01270 mm)
Volatile Organic Content (VOC)	731 g/l	731 g/l

Table 2 - Ordering Information

Product	Weight (grams)	Packaging	Part Number
CHO-BOND 1085	400	1 pint can	50-01-1085-0000
CHO-BOND 1086	10	3 dram glass vial	50-10-1086-0000
	95	4 fluid ounce glass bottle	50-04-1086-0000
	375	1 pint can	50-01-1086-0000

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